

# Data line chokes Series/Type: B82793C2

The following products presented in this data sheet are being withdrawn.

Ordering Code	Substitute Product		Deadline Last Orders	Last Shipments
B82793C2474N215		2014-08-08	2014-11-30	2015-02-28
B82793C2473N201		2014-08-08	2014-11-30	2015-02-28
B82793C2225N265		2014-08-08	2014-11-30	2015-02-28

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Ordering Code	Substitute Product		Deadline Last Orders	Last Shipments
B82793C2113N201		2014-08-08	2014-11-30	2015-02-28

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B82793C2

### Data and signal line chokes

Common-mode chokes, ring core

<u>SMD</u>

# Rated voltage 42 V AC/80 V DC Rated inductance 0.011 mH to 2.2 mH Rated current 100 mA to 200 mA

## Construction

- Current-compensated ring core quad choke
- Ferrite core
- LCP case (UL 94 V-0)
- Silicone potting
- Bifilar winding

### Features

- Suitable for reflow soldering
- RoHS-compatible

## Function

Suppression of asymmetrical interference coupled in on lines, whereas data signals up to some MHz can pass unaffectedly

## Applications

- Telecom applications
- ISDN systems

## Terminals

- Base material CuSn6
- Layer composition Ni, Sn
- Hot-dipped

## Marking

- Marking on component: Manufacturer, ordering code, date of manufacture (YWWD)
- Minimum data on reel: Manufacturer, ordering code, L value and tolerance, quantity, date of packing

### Delivery mode and packing unit

- 16-mm blister tape, wound on 330-mm Ø reel
- Packing unit: 1000 pcs./reel



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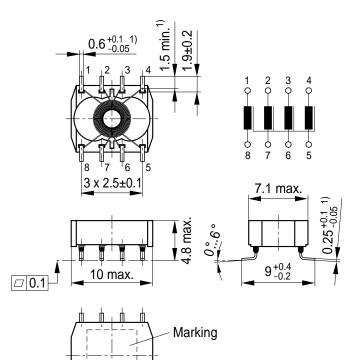
B82793C2

# Data and signal line chokes

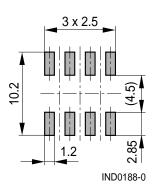
## Common-mode chokes, ring core

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## Dimensional drawing and pin configuration



### Layout recommendation



1) Soldering area

IND0187-L-E

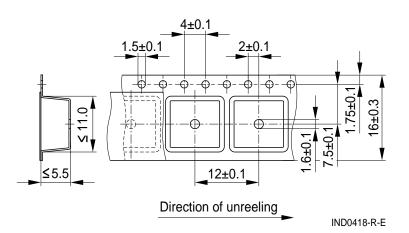
Dimensions in mm

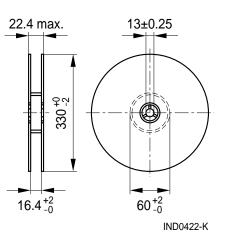
Reel

## **Taping and packing**

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Blister tape





Dimensions in mm

Please read *Cautions and warnings* and *Important notes* at the end of this document.

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# Technical data and measuring conditions

Rated voltage V <sub>R</sub>	42 V AC (50/60 Hz) / 80 V DC
Rated temperature T <sub>R</sub>	60 °C
Rated current I <sub>R</sub>	Referred to 50 Hz and rated temperature
Rated inductance L <sub>R</sub>	Measured with Agilent 4284A at 0.1 mA, 20 °C Measuring frequency: $L_R \le 1 \text{ mH} = 100 \text{ kHz}$ $L_R > 1 \text{ mH} = -10 \text{ kHz}$ Inductance is specified per winding.
Inductance tolerance	–30/+50% at 20 °C
Inductance decrease $\Delta L/L_0$	< 10% at DC magnetic bias with I <sub>R</sub> , 20 °C
Stray inductance L <sub>stray,typ</sub>	Measured with Agilent 4284A at 5 mA, 20 °C, typical values Measuring frequency: $L_R \le 11 \ \mu H = 1 \ MHz$ $L_R > 11 \ \mu H = 100 \ kHz$
DC resistance R <sub>typ</sub>	Measured at 20 °C, typical values, specified per winding
Solderability (lead-free)	Sn96.5Ag3.0Cu0.5: (245 ±5) °C, (3 ±0.3) s Wetting of soldering area ≥ 95% (to IEC 60068-2-58)
Resistance to soldering heat	(260 ±5) °C, (10 ±1) s (to IEC 60068-2-58)
Climatic category	40/125/56 (to IEC 60068-1)
Storage conditions (packaged)	–25 °C … +40 °C, ≤75% RH
Weight	Approx. 0.4 g

# **Characteristics and ordering codes**

L <sub>R</sub>	L <sub>stray,typ</sub>	I <sub>R</sub>	R <sub>typ</sub>	V <sub>test</sub>	Ordering code
mH	nH	mA	mΩ	V DC, 2 s	
0.011	120	200	60	750	B82793C2113N201
0.047	170	150	150	750	B82793C2473N201
0.47	170	100	350	750	B82793C2474N215
2.2	220	100	400	750	B82793C2225N265

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# Data and signal line chokes

# Common-mode chokes, ring core

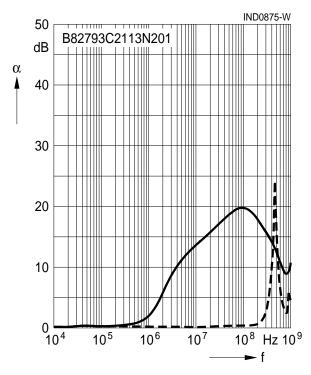
<u>SMD</u>

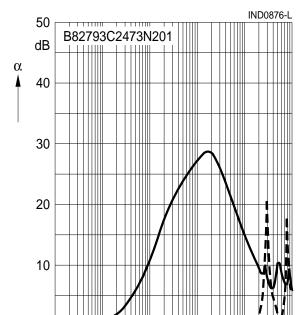
 $L_{R} = 0.047 \text{ mH}$ 

**Insertion loss**  $\alpha$  (typical values at  $|Z| = 50 \Omega$ , 20 °C)

— asymmetrical, all branches in parallel (common mode)

 $L_{R} = 0.011 \text{ mH}$ 





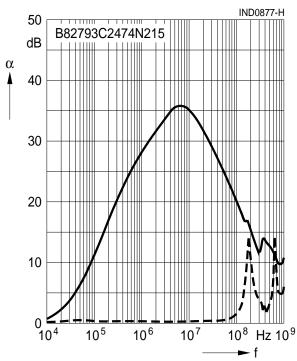
10<sup>6</sup>

10<sup>7</sup>

10<sup>8</sup> Hz 10<sup>9</sup>

► f

L<sub>R</sub> = 0.47 mH

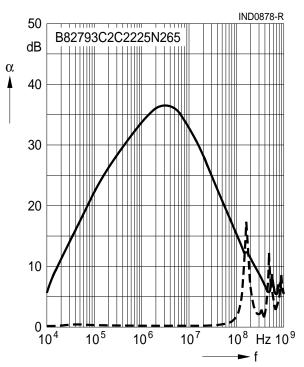




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10<sup>4</sup>

10<sup>5</sup>



# → f

Please read *Cautions and warnings* and *Important notes* at the end of this document.

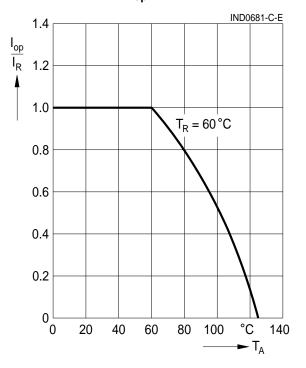
# **②TDK**

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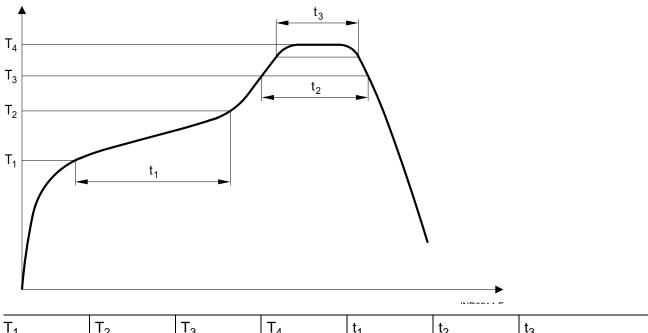
<u>SMD</u>

# Current derating $I_{op}/I_R$ versus ambient temperature



# Recommended reflow soldering curve

Pb-free solder material (based on JEDEC J-STD 020C)



'1	'2	13	'4	4	<b>1</b> 2	<b>1</b> 3
°C	°C	°C	°C	S	S	S
150	200	217	250	< 110	< 90	< 30 @ T <sub>4</sub> –5 °C

Time from 25 °C to  $T_4$ : max 300 s Maximal numbers of reflow cycles: 3

Please read *Cautions and warnings* and *Important notes* at the end of this document.

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#### **Cautions and warnings**

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.



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